

01-10-2007



FORM PTO-1595

103359518

 RECORDATION FORM COVER SHEET
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 U.S. Department of Commerce
 Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Mutsumi Masumoto

Additional name(s) attached? ☐ Yes ☒ No

2. Name and Address of receiving party(ies):

 Name: Texas Instruments Incorporated
 Internal Address: P. O. Box 655474, M/S 3999
 Street Address: 7839 Churchill Way

City: Dallas

State: Texas

Zip: 75265

Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of Conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: November 1, 2006

4. Application number(s) or patent number(s). Serial No. 11/552,351

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ NoAdditional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

 Name: Yingsheng Tung
 Internal Address: P. O. Box 655474, M/S 3999
 Street Address: 7839 Churchill Way

City: Dallas

State: Texas

Zip: 75265

6. Number of applications and patents involved: 1

7. Amount of fee enclosed or authorized to be charged: \$40.00

8. Deposit account number (Attach two copies of this form if paying by deposit account): 20-0668

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Signature

Name of Person Signing: Yingsheng Tung, Reg. No. 52,305Date: 1-4-2007

Total number of pages including cover sheet, attachments, and document: 3

01/09/2007 MJANA1 00000156 200668 11552351

01 FC:8021

(40.00 DA)

ASSIGNMENT

WHEREAS, TEXAS INSTRUMENTS JAPAN, LTD. (hereinafter **TIJ**), a Japanese company having its headquarters at 24-1 Nishi-Shinjuku 6-chome, Shinjuku-ku, Tokyo, Japan, under the laws of Japan made application, in its own name, for Letters Patent in Japan in respect of an invention as set forth below;

WHEREAS, the or each below named inventor (hereinafter **INVENTOR**) is the or an inventor of the said invention;

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, having a place of business at 7839 Churchill Way, Mail Station 3999, Dallas, Texas 75251, USA, is desirous of acquiring the entire right, title and interest in and to the said invention outside of Japan, and in and to the U.S. patent application as identified hereinafter and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, by this Assignment, **TIJ** and **INVENTOR** sell and assign to the said **TEXAS INSTRUMENTS INCORPORATED**, its successors and assigns the entire right, title and interest in and to the said invention in the U.S.A. and all other countries outside Japan; in and to the U.S. patent application as identified below and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof, and the right to file applications and obtain patents in its own name in any said other country or group of countries, and to claim priority under the terms of the International Convention for the Protection of Industrial Property or any other relevant convention;

TIJ and **INVENTOR** hereby authorize and request the Commissioner of Patents to issue U.S. patents for said invention, or U.S. patents resulting therefrom, insofar as the interest of **TIJ** and **INVENTOR** is concerned to the said **TEXAS INSTRUMENTS INCORPORATED**, as assignee of the entire right, title and interest.

TIJ and **INVENTOR** further agree to communicate to **TEXAS INSTRUMENTS INCORPORATED** or to its successors, assigns and legal representatives, any facts known to **TIJ** and **INVENTOR** respecting the said invention, and at the expense of **TEXAS INSTRUMENTS INCORPORATED**, sign any and all patent applications, assignments, affidavits and other lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, testify in any legal or quasi-legal proceedings and generally do everything possible to aid said **TEXAS INSTRUMENTS INCORPORATED**, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries outside of Japan.

METHOD FOR MANUFACTURING A SEMICONDUCTOR DEVICE

Title of Invention

Japanese Serial No.: 2005-309728 Filed: 25 October 2005

U.S. Application Serial No.: 11/552,351 Filed: 24 October 2006

IN WITNESS WHEREOF, this Agreement has been executed as set forth below;

Signed at Tokyo, Japan on November 1, 2006

by **Texas Instruments Japan, Ltd.**

Name T. Yamasaki
Toshiyuki Yamasaki

Title Representative Director and President

Date November 1, 2006

and by the **INVENTOR(S):**

(1) Mutsumi Masumoto
Mutsumi Masumoto

17-9 Spa land Toyomi, Beppu-shi Oita 874-0012, Japan
Address

1 November 2006
Date

**PALM INTRANET**Day : Friday
Date: 1/5/2007
Time: 07:14:22**Application Number Information**

Application Number: 11/552351

Examiner Number: 00000 /

Assignments

Filing or 371(c) Date: 10/24/2006

Group Art Unit: 2812

IFW IMAGE

Effective Date: 10/24/2006

Class/Subclass: 438/460.000

Application Received: 10/24/2006

Lost Case: NO

Patent Number:

Interference Number:

Issue Date: 00/00/0000

Unmatched Petition: NO

Date of Abandonment: 00/00/0000

L&R Code: Secrecy Code:1

Attorney Docket Number: TI-61536

Third Level Review: NO

Secrecy Order: NO

Status: 19 /APPLICATION UNDERGOING PREEXAM PROCESSING Status Date: 10/24/2006

Confirmation Number: 1915

Oral Hearing: NO

Title of Invention: METHOD FOR MANUFACTURING A SEMICONDUCTOR DEVICE

Bar Code	PALM Location	Location Date	Charge to Loc	Charge to Name	Employee Name	Location
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**Appln
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **MASUMOTO** Docket Number: **TI-61536**

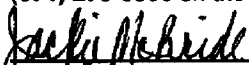
Serial No.: **11/552,351** Art Unit: **TBD**

Filed: **October 24, 2006** Examiner: **TBD**

For: **METHOD FOR MANUFACTURING A SEMICONDUCTOR DEVICE**

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office at (571) 273-8300 on the date shown below:


Jackie McBride

1-4-2007
Date

FACSIMILE COVER SHEET

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET	
<input checked="" type="checkbox"/> ASSIGNMENT (3 Pages)	
NAME OF INVENTOR(S): MASUMOTO	
RECEIPT DATE & SERIAL NO.: Serial No.: 11/552,351 Conf. No.: 1915	
TITLE OF INVENTION: METHOD FOR MANUFACTURING A SEMICONDUCTOR DEVICE	
TI FILE NO.: TI-61536	DEPOSIT ACCT. NO.: 20-0668
FAXED: 01/04/2007	
DUE:	
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